

SPECIFICATION FOR APPROVAL

CN: 1308000943

CUSTOMER : _____

PRODUCT TYPE : SMD GLASS SEALING X'TAL 3.2*2.5

NOMINAL FREQ. : 55.466670MHz

TXC P/N : AV55400003

REVISION : S1

CUSTOMER P/N : _____

PM / SALES : _____

DATE : _____

CUSTOMER SIGNATURE & Date _____

- (1) TXC requires one copy returned with signature and title of authorized individual that signifies acceptance of the attached specifications.
- (2) Orders received and accepted by TXC after return of signed copy of specification will be produced per these specifications.
- (3) Any changes to these specifications must be agreed upon by both parties and new revision of the Product Specification Sheet will be issued.
- (4) Any issuance of purchase order prior to consigning back the Approval page of "Specification Sheets" from customers will be regarded as the agreement on the contents of these specifications.

**MSL:Level 1
RoHS Compliant**

Pb used in sealing glass material is exempt from EU directive

PRODUCT SPECIFICATION SHEET

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PE/RD	QA	MFG
<i>Shih-Yung Pao</i> Shih-Yung Pao		
<i>16-Aug-13</i>		

NOTE:

- (1)Lead Free Products are "Directive 2002/95/EC of The European Parliament of 27 January 2003 on the restriction of the use of certain hazardous substances (RoHS) in electrical and electronic equipment" Compliant (Attachment: SGS Test Report).
- (2)Revision "Sx" is for engineering samples only. PE/RD's approval required.
- (3)Revision "Ax" is production ready. PE, QA and MFG's approval required

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Spec Sheet Contents

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■ ELECTRICAL SPECIFICATIONS

Standard atmospheric conditions

Unless otherwise specified, the standard range of atmospheric conditions for making measurement and tests are as follow:

Ambient temperature : $25\pm 5^{\circ}\text{C}$
 Relative humidity : 40%~70%

If there is any doubt about the results, measurement shall be made within the following limits:

Ambient temperature : $25\pm 3^{\circ}\text{C}$
 Relative humidity : 40%~70%

Measure equipment

Electrical characteristics measured by S&A250B or equivalent.

Crystal cutting type

The crystal is using AT CUT (thickness shear mode).

Unit Weight:

0.018±0.001 g/pcs

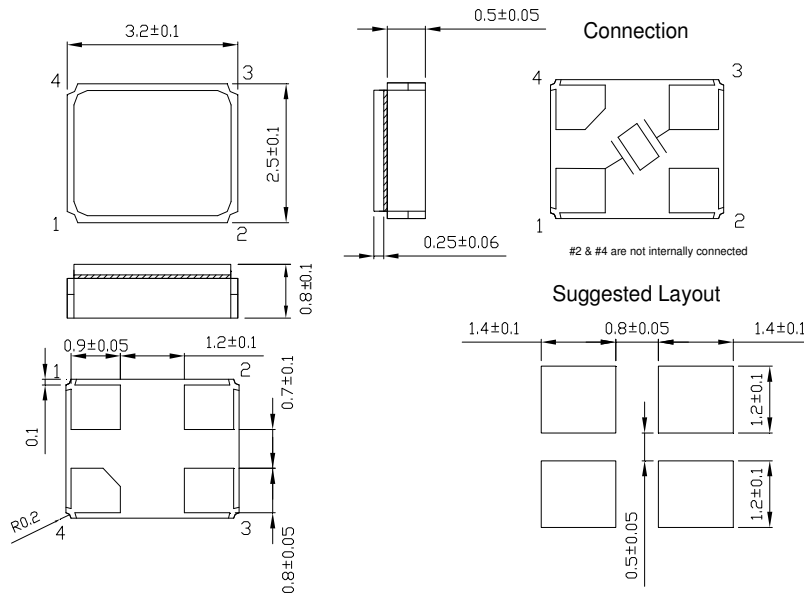
	Parameters	SYM.	Electrical Spec.				Notes
			MIN	TYP	MAX	UNITS	
1	Nominal Frequency	FL	55.466670			MHz	-
2	Oscillation Mode	-	Fundamental			-	-
3	Load Capacitance	CL	9			pF	-
4	Frequency Tolerance	-	±25			ppm	at $25^{\circ}\text{C} \pm 3^{\circ}\text{C}$
5	Frequency Stability	-	±30			ppm	Over Operating Temp. Range (Reference 25°C)
6	Operating Temperature	-	-40	~	85	$^{\circ}\text{C}$	-
7	Aging	-	±5			ppm	1st Year
8	Drive Level	DL	-	10	-	uW	-
9	Series Resonant Resistance	Rr	-	-	30	Ω	-
10	Shunt Capacitance	C0	-	-	2	pF	-
11	Insulation Resistance	-	500	-	-	M Ω	at DC 100V
12	Storage Temperature Range	-	-40	~	150	$^{\circ}\text{C}$	-

■ FACTORY LOCATION

TXC (NINGBO) CORPORATION
 NO.189 Huang Shan West Road, Beilun District,
 Ningbo Zhejiang China

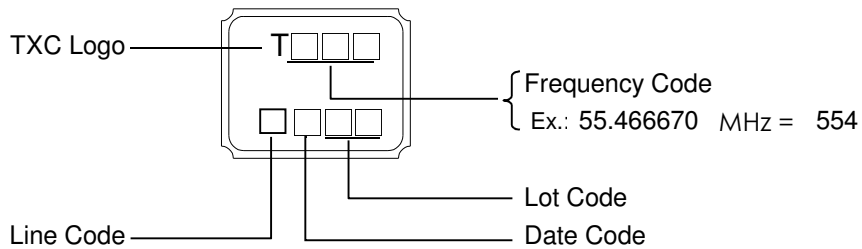
■ DIMENSIONS

(Unit:mm)



*Coplanarity of solderable areas Camber 0.10 mm Max

■ MARKING



Date Code:

YEAR \ MONTH				MONTH											
				JAN	FEB	MAR	APR	MAY	JUN	JUL	AUG	SEP	OCT	NOV	DEC
2005	2009	2013	2017	A	B	C	D	E	F	G	H	J	K	L	M
2006	2010	2014	2018	N	P	Q	R	S	T	U	V	W	X	Y	Z
2007	2011	2015	2019	a	b	c	d	e	f	g	h	j	k	l	m
2008	2012	2016	2020	n	p	q	r	s	t	u	v	w	x	y	z

*This date code will be cycled every four years

■ SUGGESTED REFLOW PROFILE

Solder melting point :220±10 °C, 60 sec. Min.

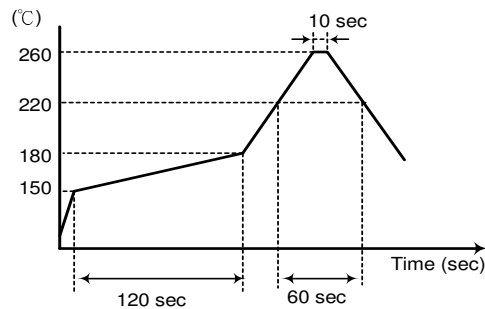
Peak Temperature: 260 ± 5 °C, 10 sec. Max.

■ SUGGESTED MANUAL SOLDER CONDITION

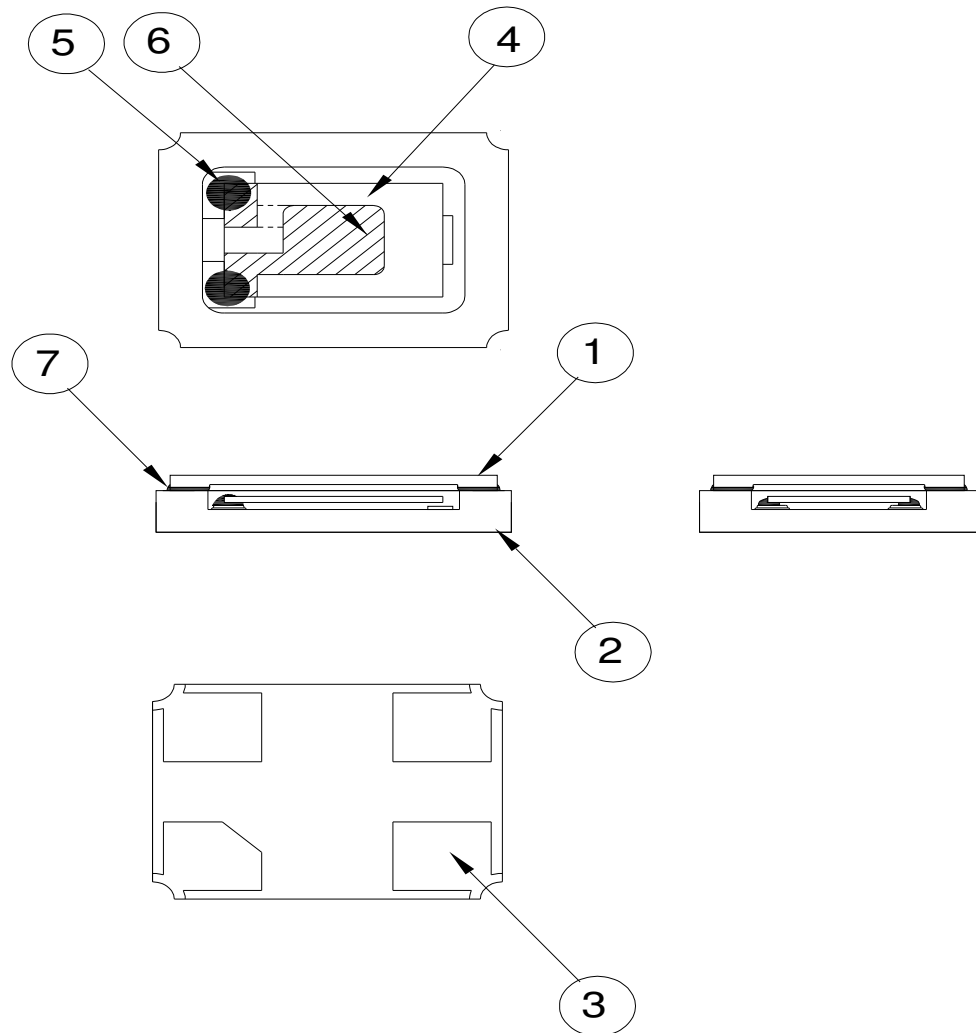
Temperature: 350 ± 10 °C

Time: 3 sec.

Re-solder times: twice

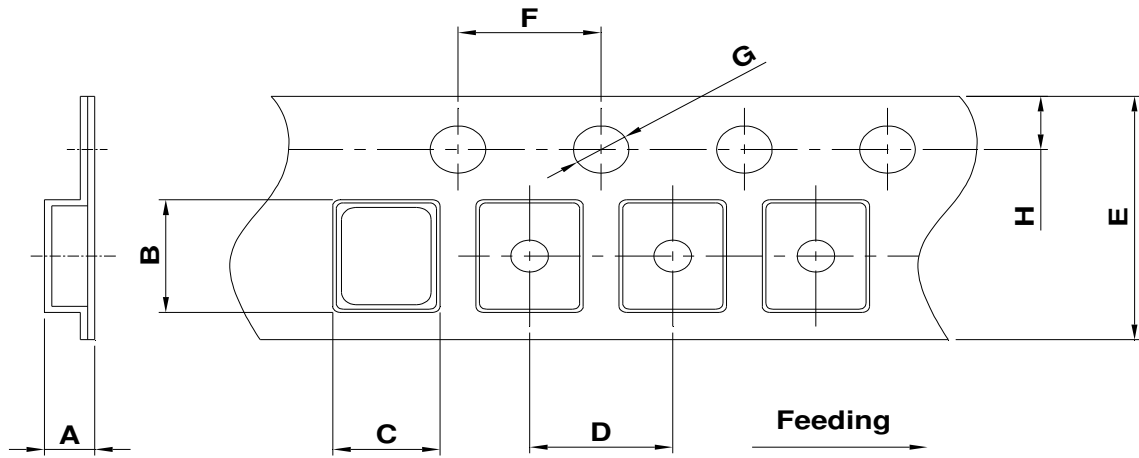


■ STRUCTURE ILLUSTRATION



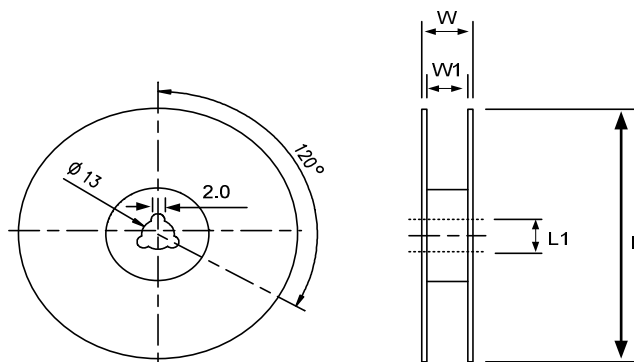
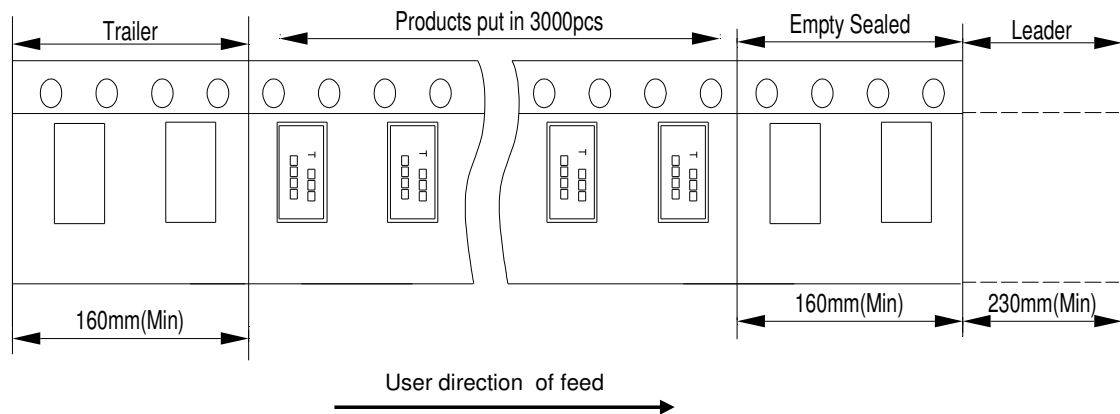
NO	COMPONENTS	MATERIALS	FINISH/SPECIFICATIONS
1	Cap	Ceramic (Al ₂ O ₃)	-
2	Package	Ceramic (Al ₂ O ₃)	-
3	PAD	Au	Tungsten metalize + Ni plating + Au plating
4	Crystal blank	SiO ₂	-
5	Conductive adhesive	Resin+Ag	-
6	Electrode	Noble Metal	-
7	Sealing Glass	Glass(PbO)	-

■ **EMBOSS CARRIER TAPE & REEL**



DIMENSIONS	A	B	C	D	E	F	G	H	
	1.65±0.10	3.40±0.10	2.70±0.10	4.00±0.10	8.00±0.20	4.00±0.10	1.55±0.10	1.75±0.10	(UNIT : mm)

REMARK :



DIMENSIONS	L	L1	W	W1	
	178±1.00	13±0.50	11.5±0.20	8±0.10	(UNIT : mm)

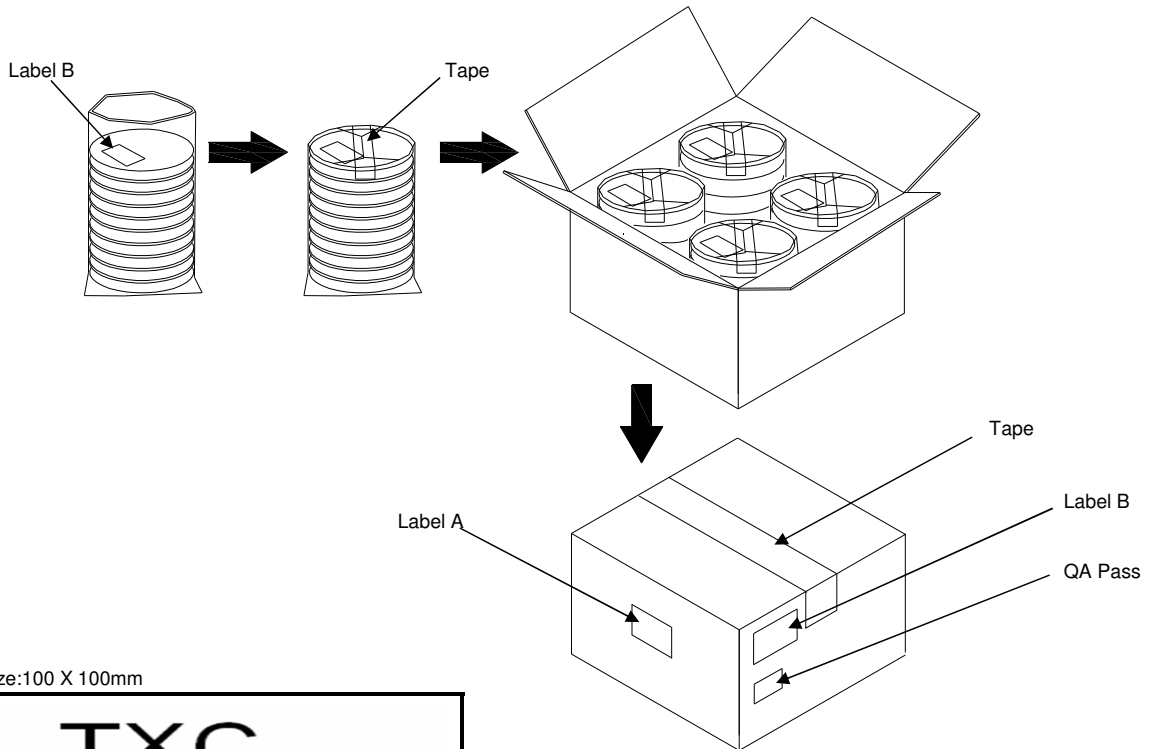
PACKING

Reel Quantity :

- 1. Reel X 6 (6 Reels)
- 2. Reel X 12 (12 Reels)
- 3. Reel X 25 (12 Reels + 13 Reels)
- 4. Reel X 50 (12 Reelsx2 + 13 Reelsx2)

Box Size:

- 1. L200 X W200 X H140mm
- 2. L200 X W200 X H250mm
- 3. L400 X W200 X H250mm
- 4. L400 X W400 X H280mm



(Label A) Size:100 X 100mm

<h1 style="margin: 0;">TXC</h1>	
Inv No: 00096815	
Po No: 21106326- 24- 1	
Part No: □□□□□□□□	
Qty: 40000 PCS	
C/No: 157- 44	

(Label B) Size:80 X 40mm

TXC CORPORATION		QA PASS
DATE CODE:	QTY:	2011/09/02
□□□□□□□□		□□□□
LOT NO:	RoHS	
□□□□□□□□		
PART NO:	HF	
□□□□□□□□		
FREQ: □□□□□□□□□□		

[STORAGE]

- 1.The storage time to be 1 year maximum.
- 2.Don't be caught in the rain.
- 3.The storage environment shall be 5°C ~40°C temperature and 30% ~ 75%RH humidity and free from the sun shine.
- 4.If customers have special requirements, we can paste labels according to it.

RELIABILITY SPECIFICATIONS (Conforms to AEC-Q200)
1.Mechanical Endurance

No.	Test Item	Test Methods	Test Criteria
1.1	Mechanical Shock	2000 G , 0.3 m Sec. ,3 times for all 3 directions.	B C
1.2	Vibration	Frequency range 10 ~ 2000 Hz Acceleration 20G Amplitude 1.52mm Sweep time 20 minute Pencilular axes each test time 4 hours (Total test time 12 hours)	B C
1.3	Terminal Strength	17.7N force for 60sec +/-1sec.	F
1.4	Board Flex	Duration time:60 Sec Minimum,Deviation:3mm	B C
1.5	Solderability	Temperature 245 °C +/- 5°C Immersing depth 0.5 mm minimum Immersion time 5 +/- 0.5 seconds Flux Rosin resin methyl alcohol solvent (1 : 4)	E

2.Environmental Endurance

No.	Test Item	Test Methods	SPEC
2.1	Resistance To Soldering Heat	Test temperature 260 +/- 5 °C Test time 10 +/- 1 sec.	BCD
2.2	High Temp. Storage	+ 85°C ± 3 °C for 1000 ± 12 Hrs	BCD
2.3	Low Temp. Storage	- 40 °C ± 3 °C for 1000 ± 12 Hrs	BCD
2.4	Temperature cycle	-40°C ~85°C, for 1000 cycles. 	BCD
2.5	Operational Life	1000 hrs @ 85± 3°C. Rated VDD applied with 1 MΩ.	BCD
2.6	High Temp & Humidity	85°C ± 3°C , RH 85% , 1000 Hrs	BCD

RELIABILITY SPECIFICATIONS

Specifications	
A	Frequency change: Within ± 5 ppm or in customer's specification.
B	Frequency change: Within ± 10 ppm or in customer's specification.
C	Equivalent series resistance(E.S.R) change: Within $\pm 15\%$ or 10Ω (larger value).
D	After conditioning , quartz crystal units shall be subjected to standard atmospheric conditions for 24 hour, and measured.
E	Minimum 95% of immersed terminal shall be covered with new uniform solder.
F	No damage on specimen

Measurement condition

Electrical characteristics measured by S&A250B or equivalent.